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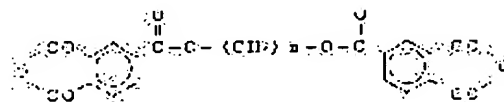
(72)Inventor : TAKEDA SHINJI  
YUSA MASAMI  
MASUKO TAKASHI  
MIYADERA YASUO

## (54) ADHESIVE FILM, ITS PRODUCTION, AND METHOD FOR ADHESION

### (57)Abstract:

**PURPOSE:** To prepare an adhesive film for die bonding which, like a conventional silver paste, enables the heat treatment in die bonding to be carried out at a relatively low temp.

**CONSTITUTION:** This adhesive film contains 100 pts.wt. polyimide resin obtd. by reacting a diamine with a tetracarboxylic dianhydride component contg. at least 70mol% tetracarboxylic dianhydride of the formula (wherein (n) is an integer of 2-20), 1-200 pts.wt. epoxy resin, 0.02-240 pts.wt. phenol resin, 0.0001-100 pts.wt. cure accelerator, and 50-4,000 pts.wt. inorg. filler.



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